



## OptiMOS<sup>®</sup> 2 Power-Transistor

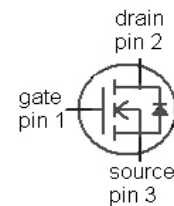
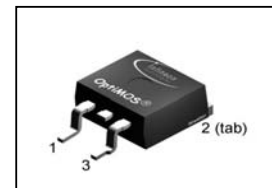
### Features

- Ideal for high-frequency dc/dc converters
- Qualified according to JEDEC<sup>1)</sup> for target applications
- N-channel - Logic level
- Excellent gate charge x  $R_{DS(on)}$  product (FOM)
- Very low on-resistance  $R_{DS(on)}$
- Superior thermal resistance
- 175 °C operating temperature
- $dv/dt$  rated
- Pb-free lead plating; RoHS compliant

### Product Summary

$V_{DS}$	25	V
$R_{DS(on),max}$ (SMD version)	3.9	m $\Omega$
$I_D$	80	A

PG-TO263



Type	Package	Marking
IPB04N03LA G	PG-TO263	04N03LA

Maximum ratings, at  $T_j=25\text{ °C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	$I_D$	$T_C=25\text{ °C}^{2)}$	80	A
		$T_C=100\text{ °C}$	80	
Pulsed drain current	$I_{D,pulse}$	$T_C=25\text{ °C}^{3)}$	385	
Avalanche energy, single pulse	$E_{AS}$	$I_D=77\text{ A}$ , $R_{GS}=25\ \Omega$	290	mJ
Reverse diode $dv/dt$	$dv/dt$	$I_D=80\text{ A}$ , $V_{DS}=20\text{ V}$ , $di/dt=200\text{ A}/\mu\text{s}$ , $T_{j,max}=175\text{ °C}$	6	kV/ $\mu\text{s}$
Gate source voltage <sup>4)</sup>	$V_{GS}$		$\pm 20$	V
Power dissipation	$P_{tot}$	$T_C=25\text{ °C}$	107	W
Operating and storage temperature	$T_j$ , $T_{stg}$		-55 ... 175	°C
IEC climatic category; DIN IEC 68-1			55/175/56	

<sup>1)</sup> J-STD20 and JESD22



Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

### Thermal characteristics

Thermal resistance, junction - case	$R_{thJC}$		-	-	1.4	K/W
SMD version, device on PCB	$R_{thJA}$	minimal footprint	-	-	62	
		6 cm <sup>2</sup> cooling area <sup>5)</sup>	-	-	40	

### Electrical characteristics, at $T_j=25\text{ }^\circ\text{C}$ , unless otherwise specified

#### Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}, I_D=1\text{ mA}$	25	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=60\text{ }\mu\text{A}$	1.2	1.6	2	
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=25\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ }^\circ\text{C}$	-	0.1	1	$\mu\text{A}$
		$V_{DS}=25\text{ V}, V_{GS}=0\text{ V}, T_j=125\text{ }^\circ\text{C}$	-	10	100	
Gate-source leakage current	$I_{GSS}$	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$	-	10	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=4.5\text{ V}, I_D=55\text{ A},$ SMD version	-	5.1	6.4	m $\Omega$
		$V_{GS}=10\text{ V}, I_D=55\text{ A},$ SMD version	-	3.2	3.9	
Gate resistance	$R_G$		-	1.1	-	$\Omega$
Transconductance	$g_{fs}$	$ V_{DS} >2 I_D R_{DS(on)max},$ $I_D=55\text{ A}$	43	85	-	S

<sup>2)</sup> Current is limited by bondwire; with an  $R_{thJC}=1.4\text{ K/W}$  the chip is able to carry 125

<sup>3)</sup> See figure 3

<sup>4)</sup>  $T_{j,max}=150\text{ }^\circ\text{C}$  and duty cycle  $D < 0.25$  for  $V_{GS} < -5\text{ V}$

<sup>5)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70



## IPB04N03LA G

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Dynamic characteristics**

Input capacitance	$C_{iss}$	$V_{GS}=0\text{ V}, V_{DS}=15\text{ V},$ $f=1\text{ MHz}$	-	2915	3877	pF
Output capacitance	$C_{oss}$		-	1236	1643	
Reverse transfer capacitance	$C_{rss}$		-	175	263	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=15\text{ V}, V_{GS}=10\text{ V},$ $I_D=20\text{ A}, R_G=2.7\ \Omega$	-	13	19	ns
Rise time	$t_r$		-	4.5	7.0	
Turn-off delay time	$t_{d(off)}$		-	38	57	
Fall time	$t_f$		-	5.4	8.1	

**Gate Charge Characteristics<sup>6)</sup>**

Gate to source charge	$Q_{gs}$	$V_{DD}=15\text{ V}, I_D=40\text{ A},$ $V_{GS}=0\text{ to }5\text{ V}$	-	10	13	nC
Gate charge at threshold	$Q_{g(th)}$		-	4.6	6.2	
Gate to drain charge	$Q_{gd}$		-	7.2	11	
Switching charge	$Q_{sw}$		-	12	17	
Gate charge total	$Q_g$		-	24	32	
Gate plateau voltage	$V_{plateau}$		-	3.3	-	
Gate charge total, sync. FET	$Q_{g(sync)}$	$V_{DS}=0.1\text{ V},$ $V_{GS}=0\text{ to }5\text{ V}$	-	20	27	nC
Output charge	$Q_{oss}$	$V_{DD}=15\text{ V}, V_{GS}=0\text{ V}$	-	27	35	

**Reverse Diode**

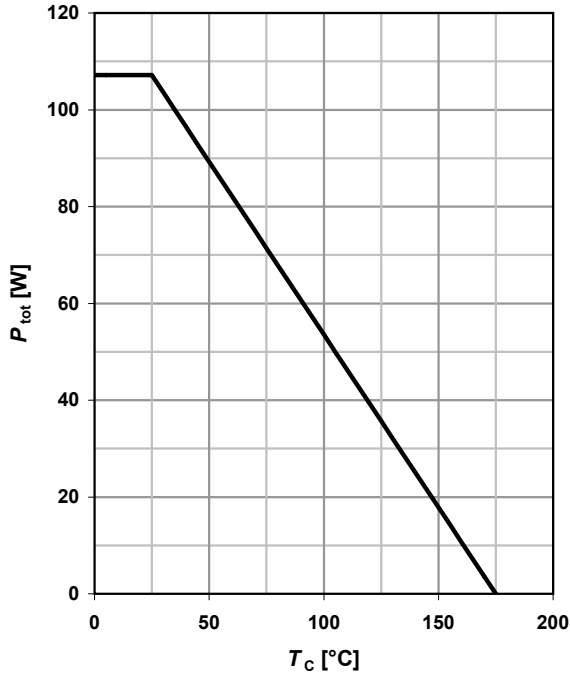
Diode continuous forward current	$I_S$	$T_C=25\text{ }^\circ\text{C}$	-	-	80	A
Diode pulse current	$I_{S,pulse}$		-	-	385	
Diode forward voltage	$V_{SD}$	$V_{GS}=0\text{ V}, I_F=80\text{ A},$ $T_j=25\text{ }^\circ\text{C}$	-	0.96	1.2	V
Reverse recovery charge	$Q_{rr}$	$V_R=15\text{ V}, I_F=I_S,$ $di_F/dt=400\text{ A}/\mu\text{s}$	-	-	15	nC

<sup>6)</sup> See figure 16 for gate charge parameter definition



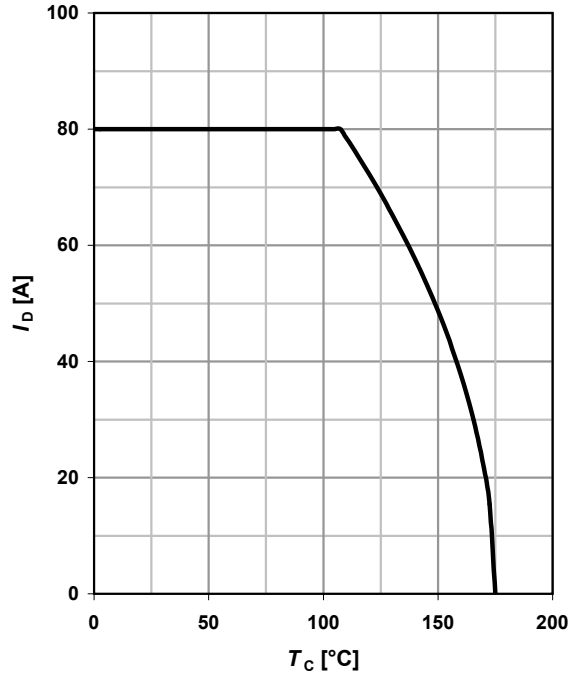
**1 Power dissipation**

$P_{tot}=f(T_C)$



**2 Drain current**

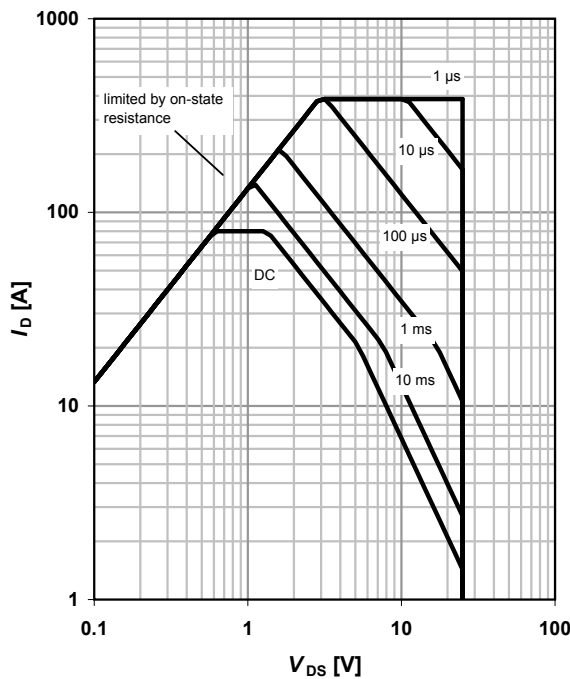
$I_D=f(T_C); V_{GS} \geq 10\text{ V}$



**3 Safe operating area**

$I_D=f(V_{DS}); T_C=25\text{ °C}; D=0$

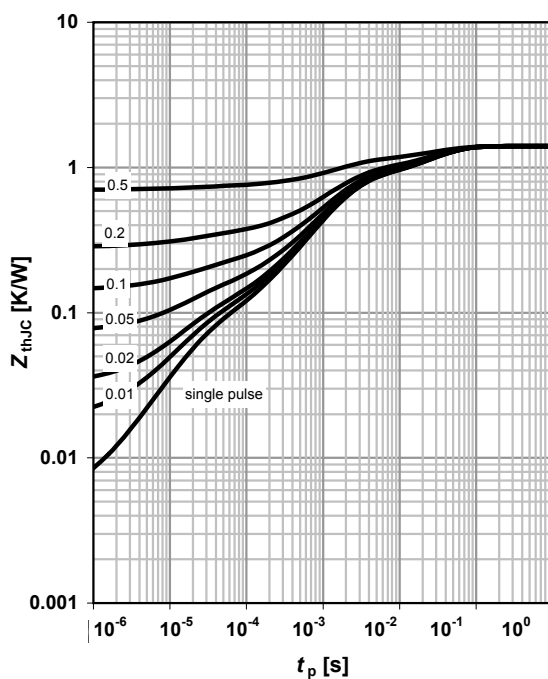
parameter:  $t_p$



**4 Max. transient thermal impedance**

$Z_{thJC}=f(t_p)$

parameter:  $D=t_p/T$

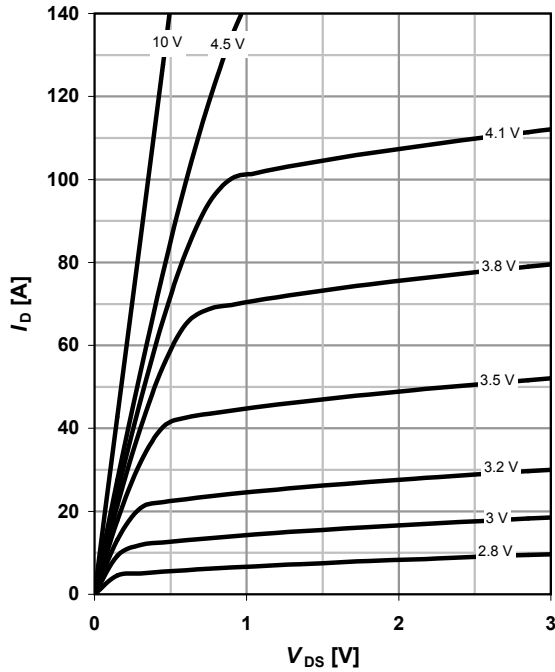




**5 Typ. output characteristics**

$I_D = f(V_{DS}); T_j = 25\text{ }^\circ\text{C}$

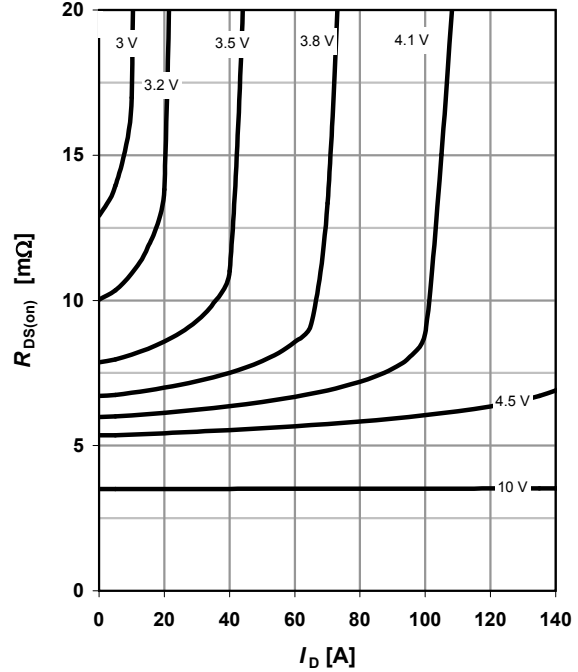
parameter:  $V_{GS}$



**6 Typ. drain-source on resistance**

$R_{DS(on)} = f(I_D); T_j = 25\text{ }^\circ\text{C}$

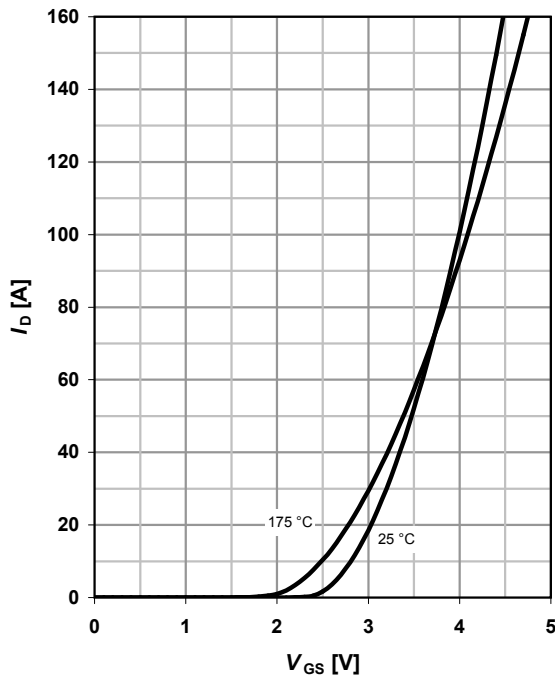
parameter:  $V_{GS}$



**7 Typ. transfer characteristics**

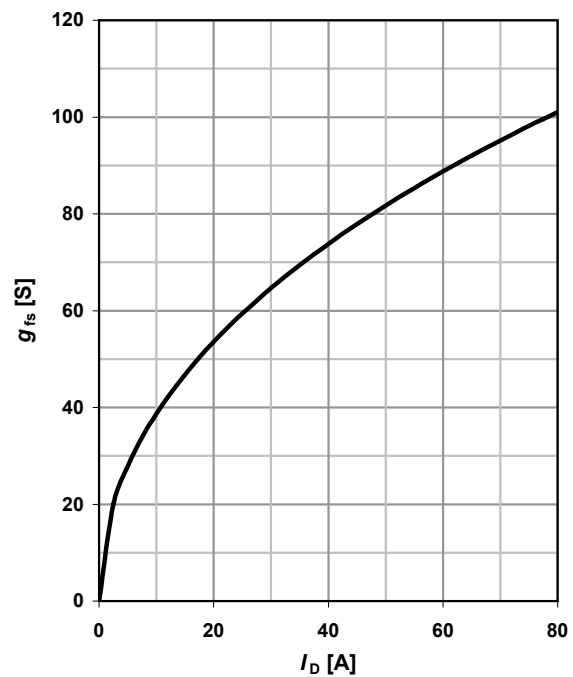
$I_D = f(V_{GS}); |V_{DS}| > 2|I_D|R_{DS(on)max}$

parameter:  $T_j$



**8 Typ. forward transconductance**

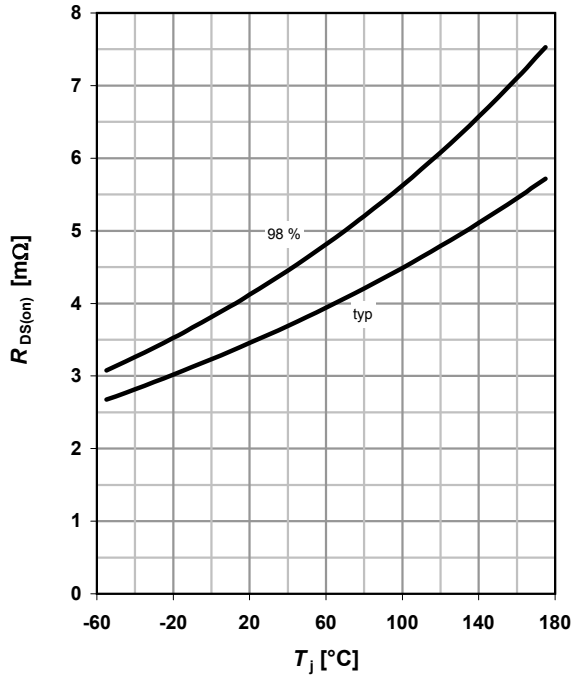
$g_{fs} = f(I_D); T_j = 25\text{ }^\circ\text{C}$





**9 Drain-source on-state resistance**

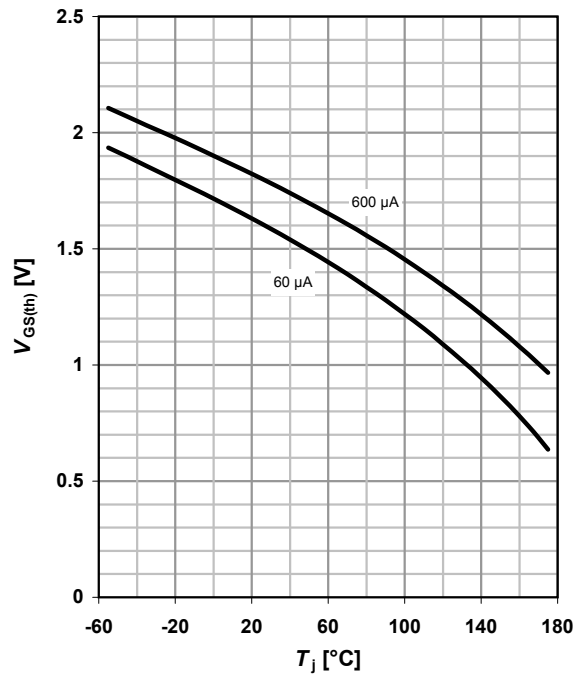
$R_{DS(on)} = f(T_j); I_D = 55 \text{ A}; V_{GS} = 10 \text{ V}$



**10 Typ. gate threshold voltage**

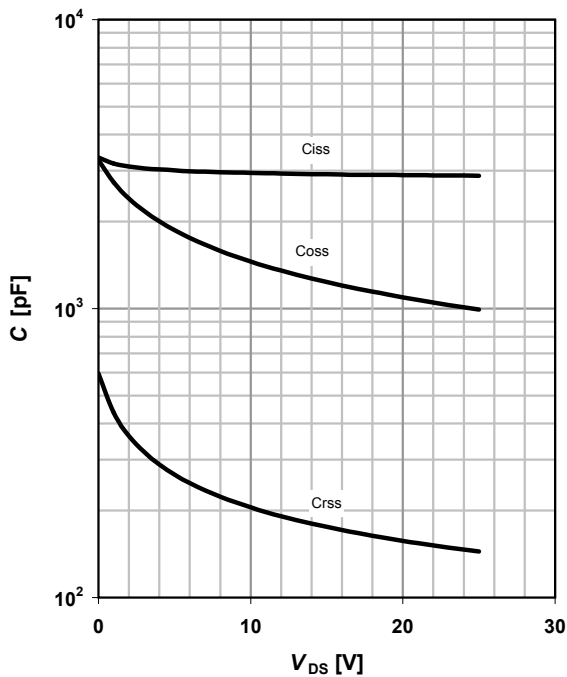
$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$

parameter:  $I_D$



**11 Typ. capacitances**

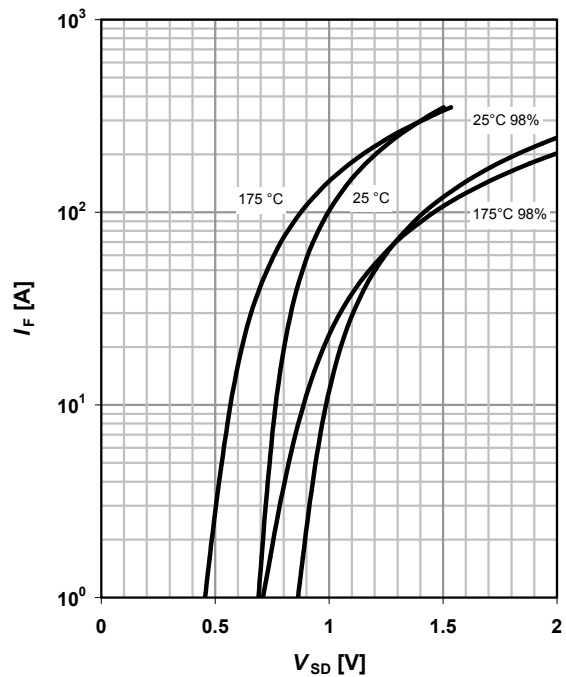
$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$



**12 Forward characteristics of reverse diode**

$I_F = f(V_{SD})$

parameter:  $T_j$

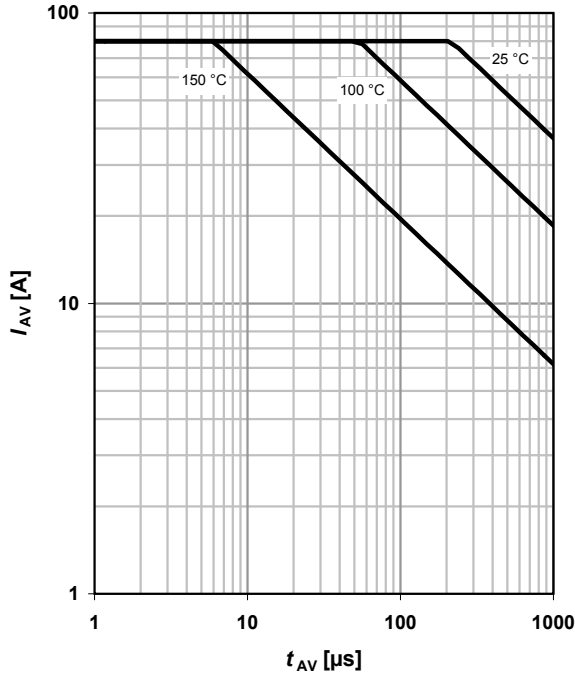




**13 Avalanche characteristics**

$I_{AS}=f(t_{AV}); R_{GS}=25 \Omega$

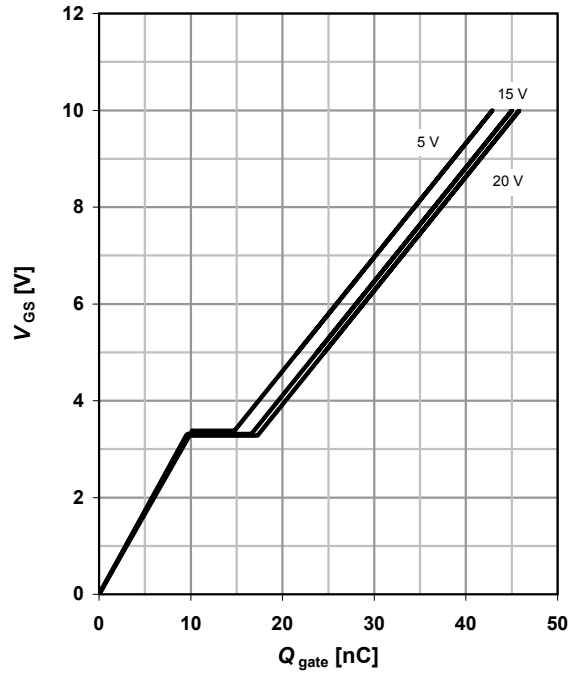
parameter:  $T_{j(start)}$



**14 Typ. gate charge**

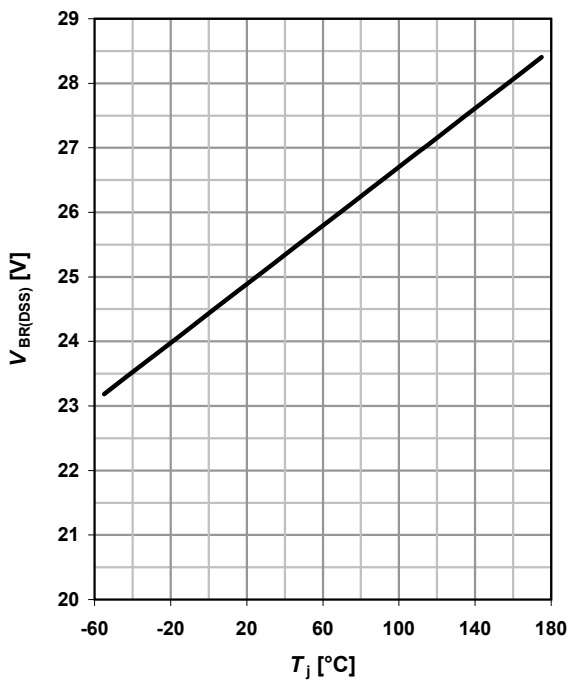
$V_{GS}=f(Q_{gate}); I_D=40 \text{ A pulsed}$

parameter:  $V_{DD}$

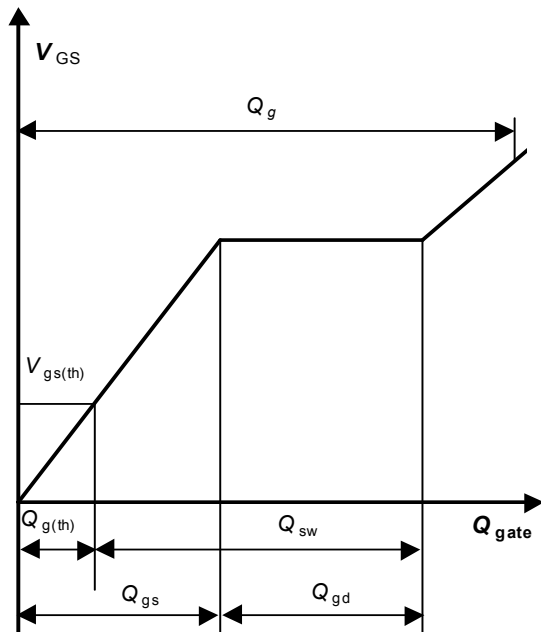


**15 Drain-source breakdown voltage**

$V_{BR(DSS)}=f(T_j); I_D=1 \text{ mA}$

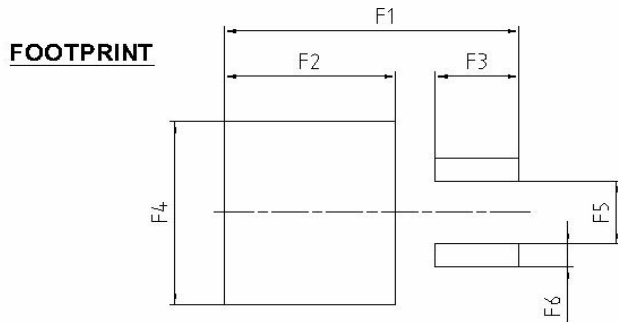
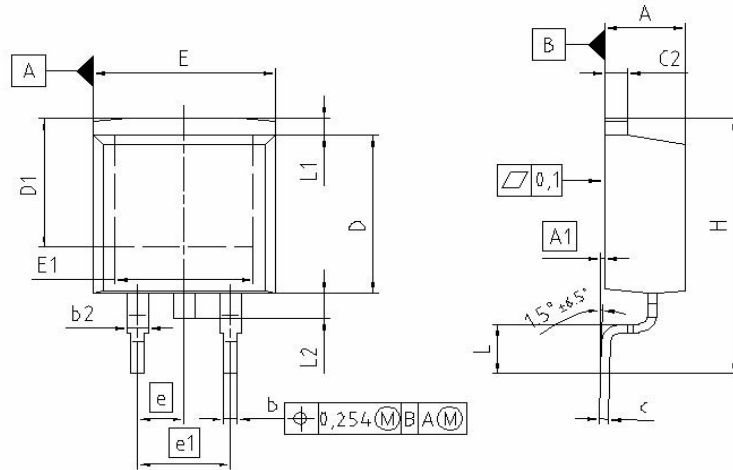


**16 Gate charge waveforms**





PG-TO263-3-2/TO263-3-5/TO263-3-22: Outlines



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.300	4.572	0.169	0.180
A1	0.000	0.254	0.000	0.010
b	0.850	0.850	0.026	0.033
b2	0.950	1.321	0.037	0.052
c	0.330	0.650	0.013	0.026
c2	0.170	1.400	0.046	0.055
D	8.509	9.450	0.335	0.372
D1	7.100	-	0.280	-
E	9.800	10.312	0.386	0.406
E1	6.500	-	0.256	-
e	2.540		0.100	
e1	5.080		0.200	
N	2		2	
H	14.605	15.875	0.575	0.625
L	2.200	3.000	0.087	0.118
L1	-	1.600	-	0.063
L2	1.000	1.778	0.039	0.070
F1	16.050	16.250	0.632	0.640
F2	9.300	9.500	0.366	0.374
F3	4.500	4.700	0.177	0.185
F4	10.700	10.900	0.421	0.429
F5	3.630	3.830	0.143	0.151
F6	1.100	1.300	0.043	0.051

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